



**Features**

- Surface Mounting Design 6.2×3.2×2.3mm
- High Current Handling Capability 1,000A @ 8/20 μ s
- High Voltage Handling Capability 6,000V @ 10/700 μ s
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level: Level 1

**Application Information**

- xDSL
- G · FAST

**Agency Approvals**

Icon	Description
<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003
	Mean lead free
	Compliance with UL497B, Certificated E232249

**Electrical Parameter**

DC Breakdown Voltage <sup>1)2)4)</sup>	100V/s	360-540	V
Impulse Spark-over Voltage <sup>4)</sup>	At 1kV/μs	for 99 % of measured values	≤ 1000
	At 1kV/μs	Typical values of distribution	≤ 900
Impulse Discharge Current <sup>3)5)</sup>	8/20μs 10 operations [5x (+) & 5x (-)]	1,000	A
Impulse Discharge Voltage <sup>3)4)</sup>	10/700μs 10 operations [5x (+) & 5x (-)]	6,000	V
Arc Voltage <sup>4)</sup>	At 1A	~8	V
Insulation Resistance <sup>4)</sup>	DC=100V	≥1	GΩ
Capacitance at 1MHz <sup>4)</sup>	V <sub>DC</sub> =0.5V	≤1.5	pF
Weight		~0.2	g
Operating and Storage Temperature		-40-90	°C
Marking		Without	

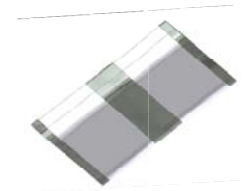
1) At delivery AQL 0.65 level II GB/T 2828.1-2003

2) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12 and IEC 61643-21

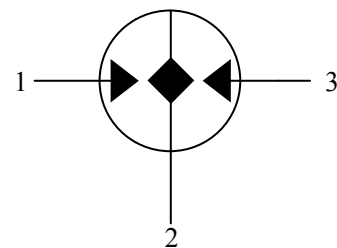
4) Tip electrode "1" or "3" to center electrode "2"

5) Total Currents through center electrode 2, half value through each Tip electrode "1"、"3" .

**Exterior**


SMD

**Package (Top View)**

**Schematic Symbol**


**Part Numbering System**

B3Y      471      M  
 (1)      (2)      (3)

- (1) Bencent 3-Electrode SMD Gas Discharge Tube  
 (2) Series: DC Breakdown Voltage, e.g.:  $471=47 \times 10^1=470V$   
 (3) Tolerance is DC Breakdown Voltage,  $M=\pm 20\%$ ,  $N=\pm 30\%$

**Product Characteristics**

Lead Material	Copper
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated

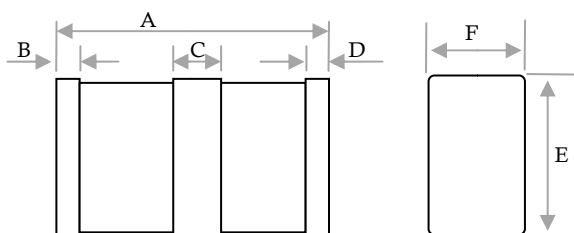
**Environmental Reliability Characteristics**

Testing items	Technical standards
High Temperature Storage Test	Temperature: 90°C Time: 2H
Low Temperature Storage Test	Temperature: -40°C Time: 2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45min
Resistance of soldering heat	Temperature: 260±5°C Time of dip soldering: 10s, 1time

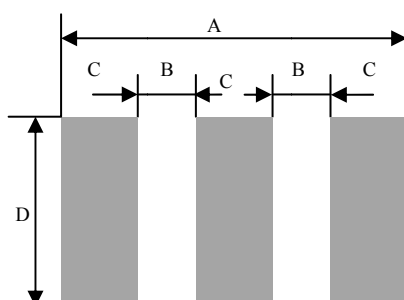
Note: Up-screen program can be specified by customer's request via contacting Bencent service

**Solderability Test**

Solderability	Solder Pot Temperature:	245°C ± 5°C
	Solder Dwell Time:	4-6 seconds

**Product Dimensions**


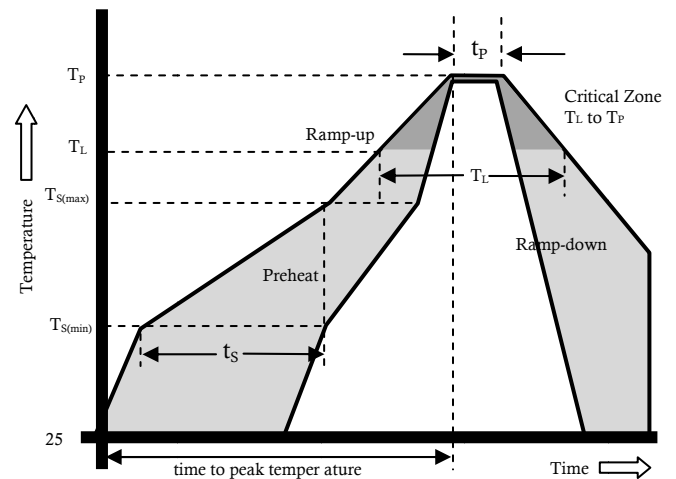
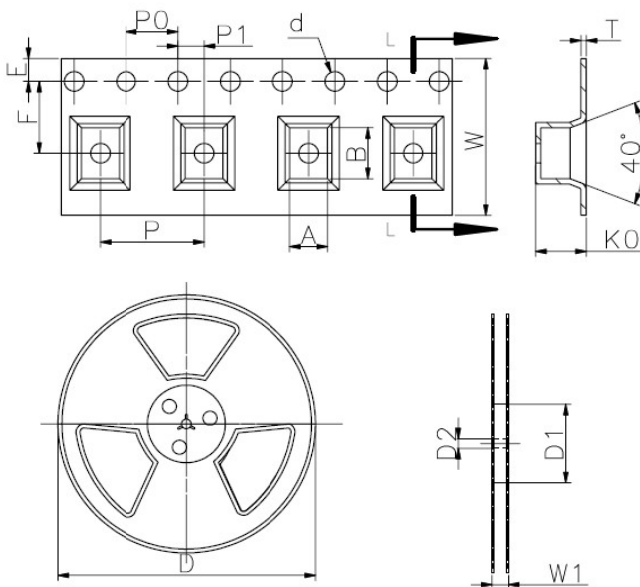
REF	mm	inch
A	6.2±0.3	0.244±0.019
B	0.3±0.1	0.019±0.004
C	1.2±0.1	0.047±0.004
D	0.3±0.1	0.019±0.004
E	3.2±0.2	0.126±0.008
F	2.3±0.2	0.091±0.008

**Recommended Soldering Pad**


REF	mm	inch
A	7.2	0.283
B	1.5	0.059
C	1.4	0.055
D	4.0	0.157

**Reflow Profile**

Reflow Condition		Pb-Free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (min to max)	60 – 180 secs
Average ramp up rate (Liquids) Tmp (T <sub>L</sub> ) to peak		3°C/second max
T <sub>S</sub> (max) to T <sub>L</sub> - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T <sub>L</sub> ) (Liquids)	217°C
	- Temperature (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature (T <sub>P</sub> )		260+0/-5 °C
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		~10 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max.
Do not exceed		260°C


**Package Reel Information**


REF	mm	inch
A	3.5±0.3	0.138±0.012
B	6.6±0.3	0.260±0.012
d	Φ1.5±0.1	Φ0.059±0.004
E	1.75±0.1	0.069±0.004
F	7.5±0.1	0.295±0.004
P	8.0±0.2	0.315±0.008
P0	4.0±0.2	0.157±0.008
P1	2.0±0.1	0.079±0.004
W	16.0±0.3	0.630±0.012
T	0.3±0.05	0.012±0.002
K0	2.7±0.1	0.094±0.004
D	Φ330.0	Φ13.0
D1	Φ50Min	Φ1.97Min
D2	Φ13±0.15	Φ0.512±0.006
W1	16.8±2.0	0.661±0.079

Outline	Reel (PCS)	Per Carton (PCS)	Reel Diameter (mm)	Carton Size(mm)		
				L	W	H
TAPING	2,000	32,000	330	360	360	380